# BAS16H, SBAS16H

# **Switching Diode**

### Features

- S Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q101 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

### MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Continuous Reverse Voltage	V <sub>R</sub>	100	Vdc
Peak Forward Current	١ <sub>F</sub>	200	mAdc
Non-Repetitive Peak Forward Surge Current, 60 Hz	I <sub>FSM(surge)</sub>	500	mAdc
Repetitive Peak Forward Current (Note 2)	I <sub>FRM</sub>	1.0	A
Non-Repetitive Peak Forward Current (Square Wave, $T_J = 25^{\circ}C$ prior to surge) $t = 1 \ \mu s$ $t = 10 \ \mu s$ $t = 100 \ \mu s$ $t = 1 \ ms$ $t = 1 \ s$	IFSM	36.0 18.0 6.0 3.0 0.7	A

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board (Note 1) $T_A = 25^{\circ}C$ Derate above 25°C	P <sub>D</sub>	200 1.57	mW mW/°C
Thermal Resistance Junction to Ambient	$R_{\theta JA}$	635	°C/W
Junction and Storage Temperature	T <sub>J</sub> , T <sub>stg</sub>	–55 to 150	°C

1. FR-4 Minimum Pad.

2. Square Wave, f = 40 kHz, PW = 200 ns Test Duration = 60 s,  $T_J$  = 25°C prior to surge. ON

## **ON Semiconductor®**

http://onsemi.com





### MARKING DIAGRAM



A6 = Specific Device Code M = Date Code

### ORDERING INFORMATION

Device	Package	Shipping†
BAS16HT1G	SOD-323 (Pb-Free)	3000 / Tape & Reel
SBAS16HT1G	SOD-323 (Pb-Free)	3000 /T ape & Reel
SBAS16HT3G	SOD-323 (Pb-Free)	10000 / Tape & Reel

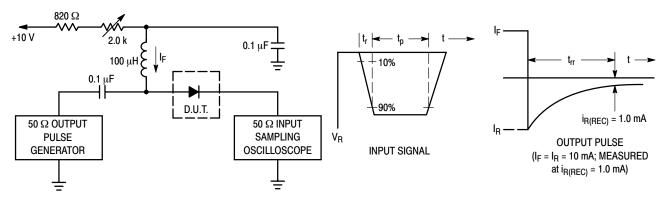
†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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## **ELECTRICAL CHARACTERISTICS** (T<sub>A</sub> = 25°C unless otherwise noted)

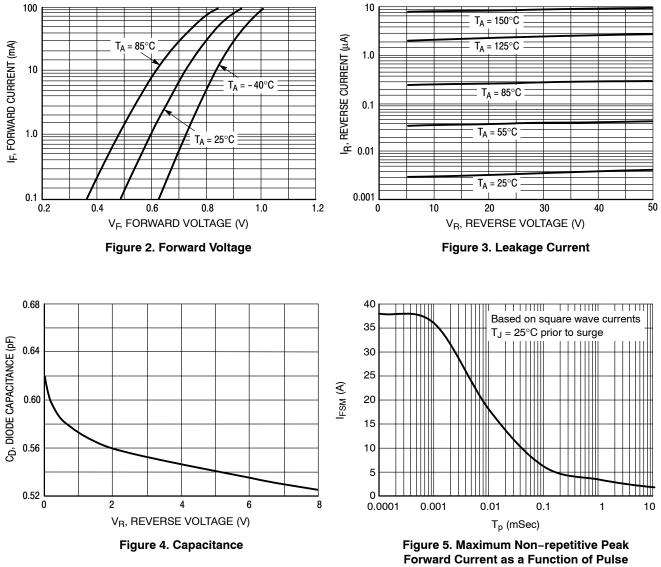
Characteristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS				
Reverse Voltage Leakage Current ( $V_R = 100 \text{ Vdc}$ ) ( $V_R = 75 \text{ Vdc}, T_J = 150^{\circ}\text{C}$ ) ( $V_R = 25 \text{ Vdc}, T_J = 150^{\circ}\text{C}$ )	I <sub>R</sub>	- - -	1.0 50 30	μAdc
Reverse Breakdown Voltage (I <sub>BR</sub> = 100 μAdc)	V <sub>(BR)</sub>	100	-	Vdc
Forward Voltage $(I_F = 1.0 \text{ mAdc})$ $(I_F = 10 \text{ mAdc})$ $(I_F = 50 \text{ mAdc})$ $(I_F = 150 \text{ mAdc})$	VF	- - -	715 855 1000 1250	mV
Diode Capacitance ( $V_R = 0, f = 1.0 \text{ MHz}$ )	C <sub>D</sub>	-	2.0	pF
Forward Recovery Voltage (I <sub>F</sub> = 10 mAdc, t <sub>r</sub> = 20 ns)	V <sub>FR</sub>	-	1.75	Vdc
Reverse Recovery Time ( $I_F = I_R = 10$ mAdc, $R_L = 50 \Omega$ )	t <sub>rr</sub>	-	6.0	ns
Stored Charge $(I_F = 10 \text{ mAdc to } V_R = 5.0 \text{ Vdc}, R_L = 500 \Omega)$	Q <sub>S</sub>	-	45	рС

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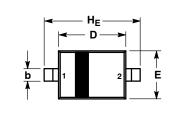
Notes: 1. A 2.0 k $\Omega$  variable resistor adjusted for a Forward Current (I<sub>F</sub>) of 10 mA. 2. Input pulse is adjusted so I<sub>R(peak)</sub> is equal to 10 mA. 3. t<sub>p</sub> » t<sub>rr</sub>

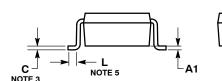




#### PACKAGE DIMENSIONS

**SOD-323** CASE 477-02 ISSUE H







NOTES:

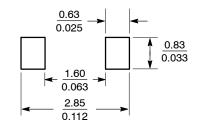
- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: MILLIMETERS.
  LEAD THICKNESS SPECIFIED PER L/F DRAWING WITH SOLDER PLATING.
- 4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.
- 5. DIMENSION L IS MEASURED FROM END OF RADIUS.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.80	0.90	1.00	0.031	0.035	0.040
A1	0.00	0.05	0.10	0.000	0.002	0.004
A3	0.15 REF		0.006 REF			
b	0.25	0.32	0.4	0.010	0.012	0.016
С	0.089	0.12	0.177	0.003	0.005	0.007
D	1.60	1.70	1.80	0.062	0.066	0.070
E	1.15	1.25	1.35	0.045	0.049	0.053
L	0.08			0.003		
He	2.30	2.50	2.70	0.090	0.098	0.105

STYLE 1:

PIN 1. CATHODE (POLARITY BAND) 2. ANODE

SOLDERING FOOTPRINT\*



\*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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